

**TOREX SEMICONDUCTOR LTD.**  
Quality Assurance Dept.

## Composition Table

Product(Pb-free): XC6420xxxxDR-G  
Typical Mass: 1.6 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.133	Silicon	83300	7440-21-3
	-	Arsenic	<1	7440-38-2
Lead pad	0.392	Nickel	245200	7440-02-0
	0.037	Silver	23300	7440-22-4
	0.004	Gold	2700	7440-57-5
Die attach	0.020	Epoxy Resin	12300	—
	0.012	Acrylic Resin	7400	—
Bonding wire	0.045	Gold	28400	7440-57-5
Resin	0.633	Silica	395500	60676-86-0
	0.123	Metal hydroxide	76800	—
	0.090	Epoxy Resin	56100	—
	0.090	Phenol Resin	56100	—
	0.020	Silica (crystal)	12800	14808-60-7

\* The component composition is based on the information provided by raw material vender.

\* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\* Any indication "-" in CAS number means "confidential."